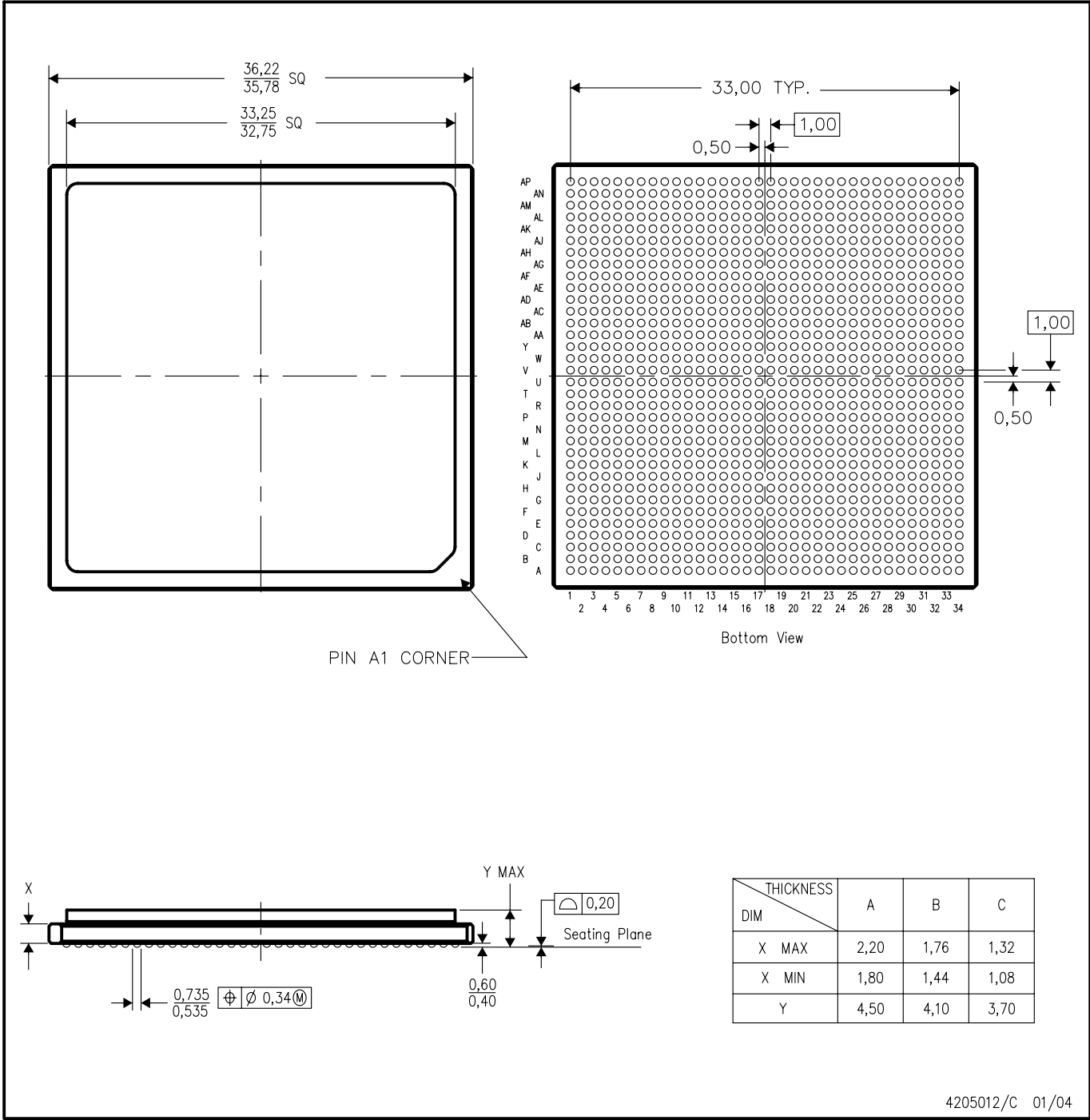


MECHANICAL DATA

GTG (S-CBGA-N1156)

CERAMIC BALL GRID ARRAY



4205012/C 01/04

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced ceramic package with a heat slug (HSL).
 - D. Flip chip application only.

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265